

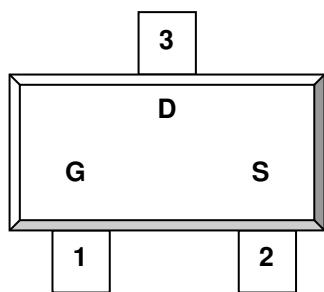
DESCRIPTION

The G2102 is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density, DMOS trench technology.

This high-density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high side switching.

PIN CONFIGURATION

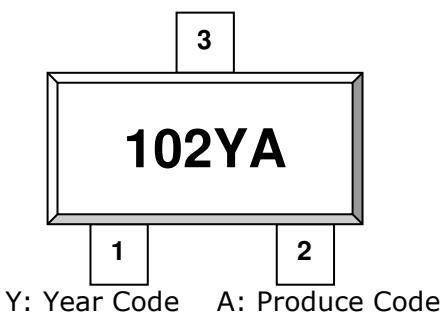
SOT-23-3L



1.Gate 2.Source 3.Drain

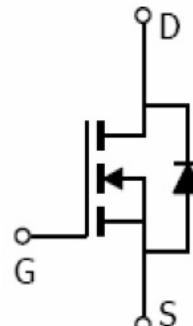
PART MARKING

SOT-23-3L



FEATURE

- 100V/3.0A, $R_{DS(ON)} = 135m\Omega$ @ $V_{GS} = 10V$
- 100V/2.5A, $R_{DS(ON)} = 140m\Omega$ @ $V_{GS} = 4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design



ABSOULTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	100	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current T _J =150°C	I _D T _A =25°C T _A =70°C	5.0 3.0	A
Pulsed Drain Current	I _{DM}	15	A
Continuous Source Current (Diode Conduction)	I _S	1.9	A
Power Dissipation	P _D T _A =25°C T _A =70°C	2.0 1.2	W
Operation Junction Temperature	T _J	-55/150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	75	°C/W

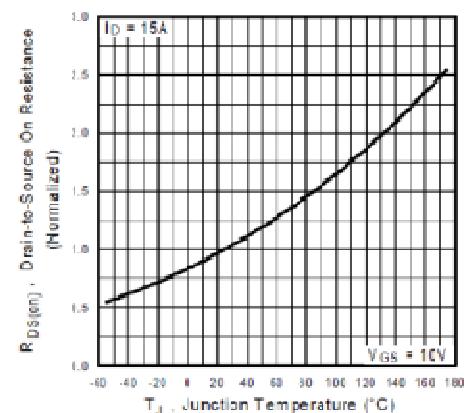
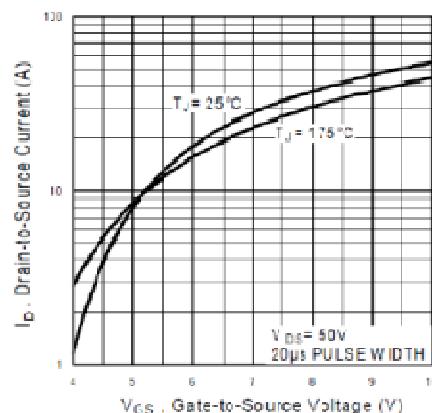
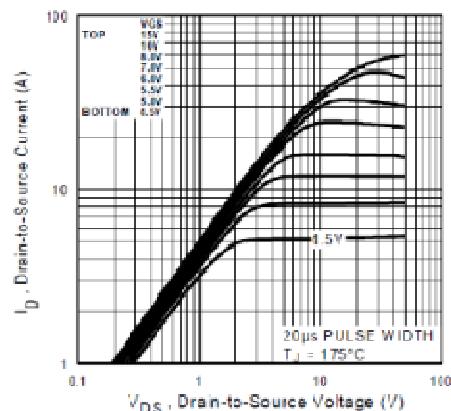
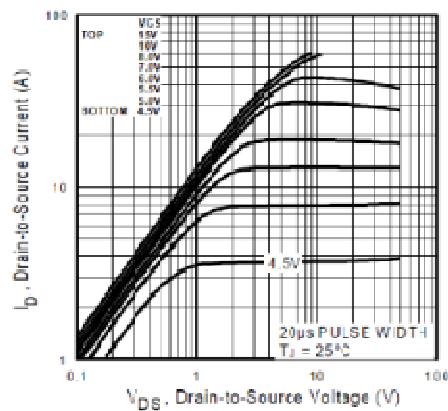
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ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1		2.5	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V			1	uA
		V _{DS} =80V, V _{GS} =0V T _J =55°C			10	
Drain-source On-Resistance	R _{DSS(on)}	V _{GS} =10V, I _D =3.0A V _{GS} =4.5V, I _D =2.0A		128 133	135 140	mΩ
Diode Forward Voltage	V _{SD}	I _S =1.7A, V _{GS} =0V			1.0	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =50V V _{GS} =10V I _D ≡2.0A			45	nC
Gate-Source Charge	Q _{gs}				7.2	
Gate-Drain Charge	Q _{gd}				22	
Input Capacitance	C _{iss}	V _{DS} =30V V _{GS} =0V F=1MHz		640		pF
Output Capacitance	C _{oss}			160		
Reverse Transfer Capacitance	C _{rss}			88		
Turn-On Time	t _{d(on)} tr	V _{DD} =30V R _L =30Ω I _D =1.0A V _{GEN} =10V R _G =6Ω		11	21	nS
Turn-Off Time	t _{d(off)} tf			10	19	
				24	44	
				21	39	

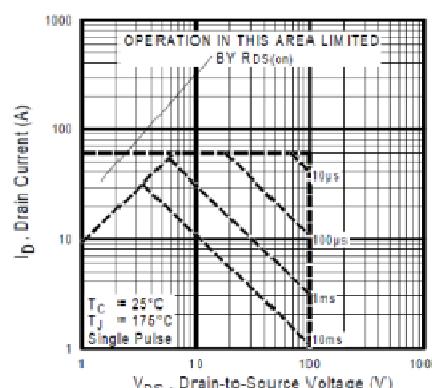
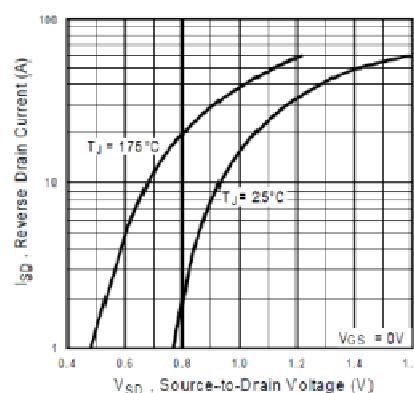
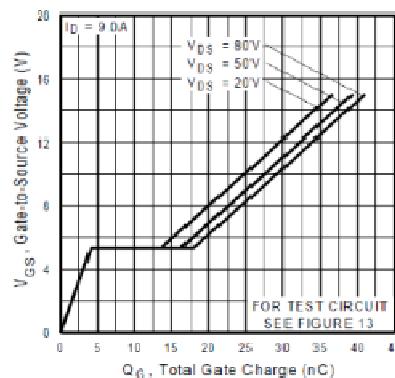
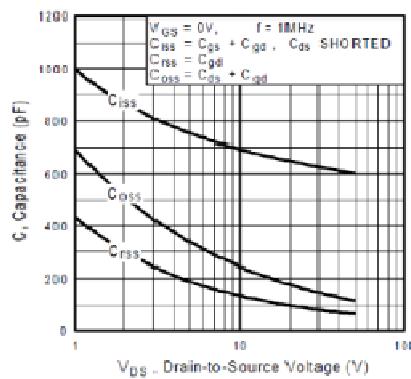
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TYPICAL CHARACTERISTICS (25°C Unless noted)



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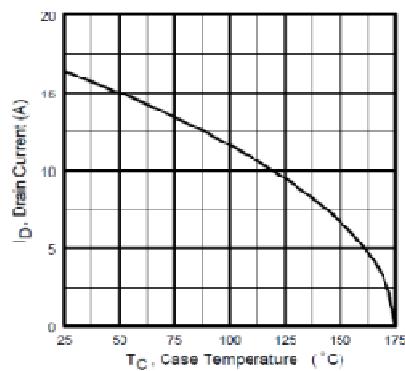


Fig 9. Maximum Drain Current Vs. Case Temperature

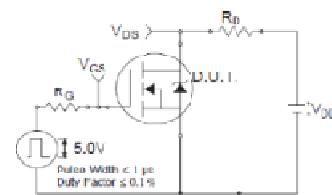


Fig 10a. Switching Time Test Circuit

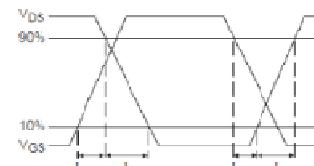


Fig 10b. Switching Time Waveforms

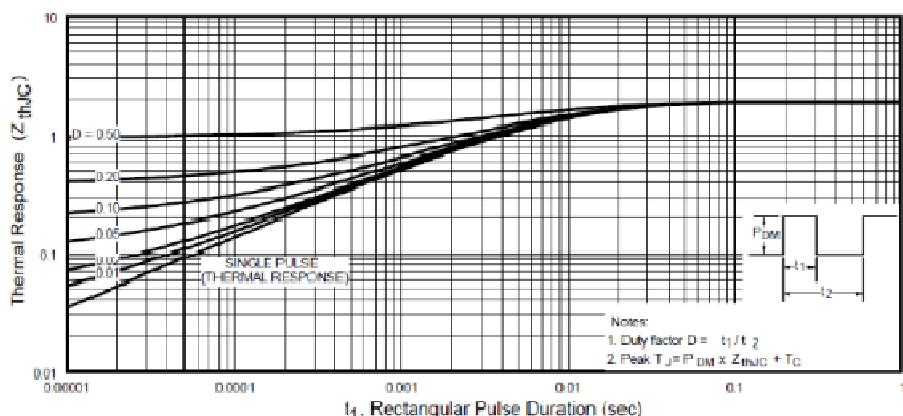
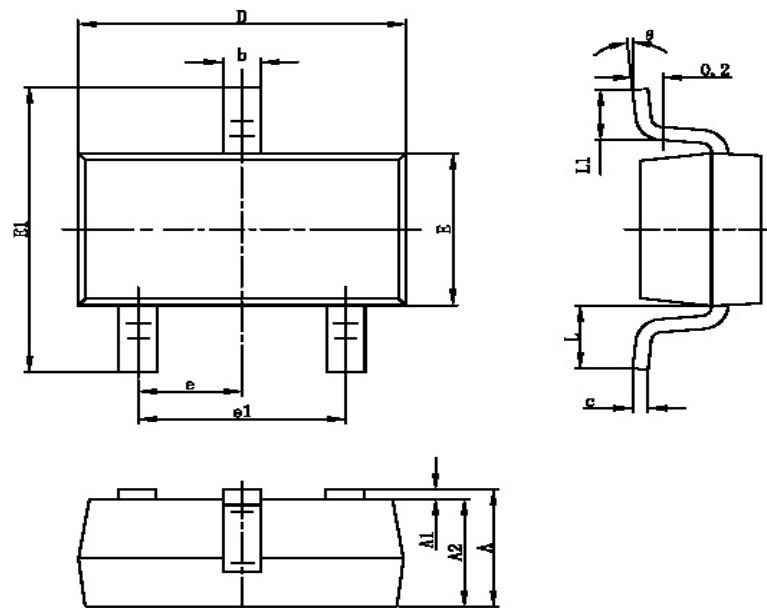


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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SOT-23-3L PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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